

Pin	Symbol	Function
1	GND	Logic ground
2	IN	Input, activates the power switch in case of logical high signal
3	V _{bb}	Positive power supply voltage, the tab is shorted to this pin
4	ST	Diagnostic feedback, low on failure
5	OUT (Load, L)	Output to the load

Maximum Ratings at T_j = 25 °C unless otherwise specified

Parameter	Symbol	Values	Unit
Supply voltage (overvoltage protection see page 3)	V_{bb}	63	V
Load dump protection $V_{LoadDump} = U_A + V_S$, $U_A = 13.5\text{ V}$ $R_I = 2\ \Omega$, $R_L = 1.1\ \Omega$, $t_d = 200\text{ ms}$, IN= low or high	$V_S^{3)}$	66.5	V
Load current (Short-circuit current, see page 4)	I_L	self-limited	A
Operating temperature range	T_j	-40 ...+150	°C
Storage temperature range	T_{stg}	-55 ...+150	
Power dissipation (DC)	P_{tot}	125	W
Inductive load switch-off energy dissipation, single pulse $T_j=150\text{ °C}$:	E_{AS}	1.7	J
Electrostatic discharge capability (ESD) (Human Body Model)	V_{ESD}	2.0	kV
Input voltage (DC)	V_{IN}	-0.5 ... +6	V
Current through input pin (DC)	I_{IN}	±5.0	mA
Current through status pin (DC)	I_{ST}	±5.0	
see internal circuit diagrams page 6...			
Thermal resistance	chip - case: R_{thJC}	≤ 1	K/W
	junction - ambient (free air): R_{thJA}	≤ 75	
	SMD version, device on pcb ⁴⁾ :	typ. 33	

³⁾ V_S is setup without DUT connected to the generator per ISO 7637-1 and DIN 40839

⁴⁾ Device on 50mm*50mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70µm thick) copper area for V_{bb} connection. PCB is vertical without blown air.

Electrical Characteristics

Parameter and Conditions at $T_j = 25\text{ °C}$, $V_{bb} = 12\text{ V}$ unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

Load Switching Capabilities and Characteristics

On-state resistance (pin 3 to 5) $I_L = 2\text{ A}$ $T_j = 25\text{ °C}$: $T_j = 150\text{ °C}$:	R_{ON}	--	30 55	38 70	$m\Omega$
Nominal load current (pin 3 to 5) ISO Proposal: $V_{ON} = 0.5\text{ V}$, $T_C = 85\text{ °C}$	$I_{L(ISO)}$	9	11	--	A
Output current (pin 5) while GND disconnected or GND pulled up, $V_{IN} = 0$, see diagram page 7, $T_j = -40...+150\text{ °C}$	$I_{L(GNDhigh)}$	--	--	1	mA
Turn-on time to 90% V_{OUT} :	t_{on}	50	160	300	μs
Turn-off time to 10% V_{OUT} :	t_{off}	10	--	80	μs
$R_L = 12\text{ }\Omega$, $T_j = -40...+150\text{ °C}$					
Slew rate on 10 to 30% V_{OUT} , $R_L = 12\text{ }\Omega$, $T_j = -40...+150\text{ °C}$	dV/dt_{on}	0.4	--	2.5	V/ μs
Slew rate off 70 to 40% V_{OUT} , $R_L = 12\text{ }\Omega$, $T_j = -40...+150\text{ °C}$	$-dV/dt_{off}$	1	--	5	V/ μs

Operating Parameters

Operating voltage ⁵⁾ $T_j = -40...+150\text{ °C}$:	$V_{bb(on)}$	4.5	--	42	V
Undervoltage shutdown $T_j = -40...+150\text{ °C}$:	$V_{bb(under)}$	2.4	--	4.5	V
Undervoltage restart $T_j = -40...+150\text{ °C}$:	$V_{bb(u\text{ rst})}$	--	--	4.5	V
Undervoltage restart of charge pump see diagram page 12 $T_j = -40...+150\text{ °C}$:	$V_{bb(ucp)}$	--	6.5	7.5	V
Undervoltage hysteresis $\Delta V_{bb(under)} = V_{bb(u\text{ rst})} - V_{bb(under)}$	$\Delta V_{bb(under)}$	--	0.2	--	V
Overvoltage shutdown $T_j = -40...+150\text{ °C}$:	$V_{bb(over)}$	42	--	52	V
Overvoltage restart $T_j = -40...+150\text{ °C}$:	$V_{bb(o\text{ rst})}$	42	--	--	V
Overvoltage hysteresis $T_j = -40...+150\text{ °C}$:	$\Delta V_{bb(over)}$	--	0.2	--	V
Overvoltage protection ⁶⁾ $I_{bb} = 40\text{ mA}$ $T_j = -40\text{ °C}$: $T_j = 25...+150\text{ °C}$:	$V_{bb(AZ)}$	60 63	-- 67	--	V
Standby current (pin 3) $V_{IN} = 0$ $T_j = -40...+25\text{ °C}$: $T_j = 150\text{ °C}$:	$I_{bb(off)}$	-- --	12 18	25 60	μA
Leakage output current (included in $I_{bb(off)}$) $V_{IN} = 0$	$I_{L(off)}$	--	6	--	μA
Operating current (Pin 1) ⁷⁾ , $V_{IN} = 5\text{ V}$	I_{GND}	--	1.1	--	mA

5) At supply voltage increase up to $V_{bb} = 6.5\text{ V}$ typ without charge pump, $V_{OUT} \approx V_{bb} - 2\text{ V}$

6) see also $V_{ON(CL)}$ in table of protection functions and circuit diagram page 7. Measured without load.

7) Add I_{ST} , if $I_{ST} > 0$, add I_{IN} , if $V_{IN} > 5.5\text{ V}$

Parameter and Conditions at T _j = 25 °C, V _{bb} = 12 V unless otherwise specified	Symbol	Values			Unit
		min	typ	max	
Protection Functions ⁸⁾					
Initial peak short circuit current limit (pin 3 to 5) ⁹⁾ , (max 400 μs if V _{ON} > V _{ON(SC)}) T _j =-40°C: T _j =25°C: T _j =+150°C:	I _{L(SCp)}	-- -- 24	-- 44 --	74 -- --	A
Repetitive short circuit current limit T _j = T _{jt} (see timing diagrams, page 10)	I _{L(SCr)}	22	35	--	A
Short circuit shutdown delay after input pos. slope V _{ON} > V _{ON(SC)} , T _j =-40..+150°C: min value valid only, if input "low" time exceeds 30 μs	t _{d(SC)}	80	--	400	μs
Output clamp (inductive load switch off) at V _{OUT} = V _{bb} – V _{ON(CL)} , I _L = 30 mA	V _{ON(CL)}	--	58	--	V
Short circuit shutdown detection voltage (pin 3 to 5)	V _{ON(SC)}	--	8.3	--	V
Thermal overload trip temperature	T _{jt}	150	--	--	°C
Thermal hysteresis	ΔT _{jt}	--	10	--	K
Inductive load switch-off energy dissipation ¹⁰⁾ , T _j Start = 150 °C, single pulse V _{bb} = 12 V: V _{bb} = 24 V:	E _{AS} E _{Load12} E _{Load24}	--	--	1.7 1.3 1.0	J
Reverse battery (pin 3 to 1) ¹¹⁾	-V _{bb}	--	--	32	V
Integrated resistor in V _{bb} line	R _{bb}	--	120	--	Ω

Diagnostic Characteristics

Open load detection current (on-condition)	$T_j = -40\text{ °C}$: $T_j = 25..150\text{ °C}$:	$I_L(OL)$	2 2	-- --	900 750	mA
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8) Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

9) Short circuit current limit for max. duration of 400 μs , prior to shutdown (see $t_{d(SC)}$ page 4)

10) While demagnetizing load inductance, dissipated energy in PROFET is $E_{AS} = \int V_{ON(CL)} * i_L(t) dt$, approx.
 $E_{AS} = \frac{1}{2} * L * I_L^2 * (\frac{V_{ON(CL)}}{V_{ON(CL)} - V_{bb}})$, see diagram page 8.

11) Reverse load current (through intrinsic drain-source diode) is normally limited by the connected load. Reverse current I_{GND} of $\approx 0.3\text{ A}$ at $V_{bb} = -32\text{ V}$ through the logic heats up the device. Time allowed under these condition is dependent on the size of the heatsink. Reverse I_{GND} can be reduced by an additional external GND-resistor (150 Ω). Input and Status currents have to be limited (see max. ratings page 2 and circuit page 7).

Parameter and Conditions at T _j = 25 °C, V _{bb} = 12 V unless otherwise specified		Symbol	Values			Unit
			min	typ	max	
Input and Status Feedback ¹²⁾						
Input turn-on threshold voltage	 T _j = -40...+150°C:	V _{IN(T+)}	1.5	--	2.4	V
Input turn-off threshold voltage	 T _j = -40...+150°C:	V _{IN(T-)}	1.0	--	--	V
Input threshold hysteresis		Δ V _{IN(T)}	--	0.5	--	V
Off state input current (pin 2)	V _{IN} = 0.4 V:	I _{IN(off)}	1	--	30	μA
On state input current (pin 2)	V _{IN} = 3.5 V:	I _{IN(on)}	10	25	50	μA
Status invalid after positive input slope (short circuit)	T _j = -40 ... +150°C:	t _{d(ST SC)}	80	200	400	μs
Status invalid after positive input slope (open load)	T _j = -40 ... +150°C:	t _{d(ST)}	350	--	1600	μs
Status output (open drain)						
Zener limit voltage	T _j = -40...+150°C, I _{ST} = +1.6 mA:	V _{ST(high)}	5.4	6.1	--	V
ST low voltage	T _j = -40...+150°C, I _{ST} = +1.6 mA:	V _{ST(low)}	--	--	0.4	

¹²⁾ If a ground resistor R_{GND} is used, add the voltage drop across this resistor.

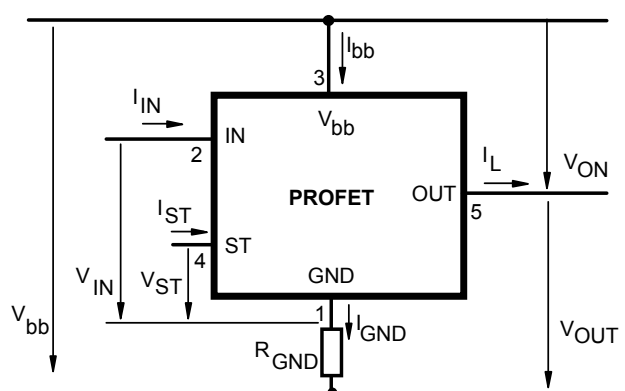
Truth Table

	Input-Level	Output level	Status
			432E2
Normal operation	L	L	H
	H	H	H
Open load	L	¹³⁾	H
	H	H	L
Short circuit to GND	L	L	H
	H	L	L
Short circuit to V _{bb}	L	H	H
	H	H	H (L ¹⁴)
Overtemperature	L	L	L
	H	L	L
Under-voltage	L	L	H
	H	L	H
Overvoltage	L	L	H
	H	L	H

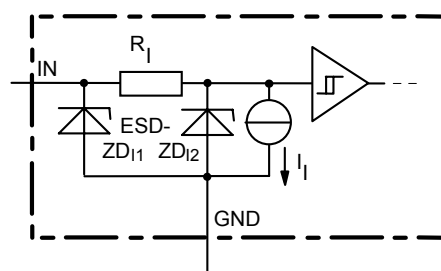
L = "Low" Level

H = "High" Level

Terms



Input circuit (ESD protection)

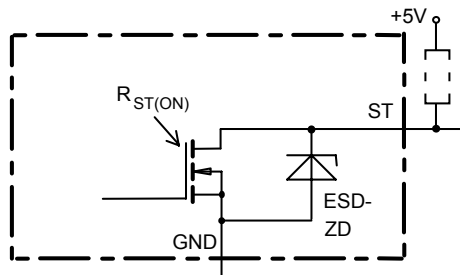


ZD_{I1} 6.1 V typ., ESD zener diodes are not designed for continuous current

¹³⁾ Power Transistor off, high impedance

¹⁴⁾ Low resistance short V_{bb} to output may be detected by no-load-detection

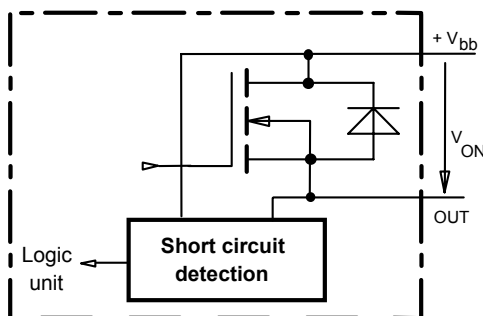
Status output



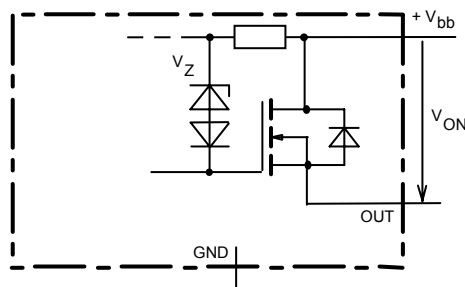
ESD-Zener diode: 6.1 V typ., max 5 mA;
 $R_{ST(ON)} < 250 \, \Omega$ at 1.6 mA, ESD zener diodes are not designed for continuous current

Short Circuit detection

Fault Condition: $V_{ON} > 8.3 \, \text{V}$ typ.; IN high

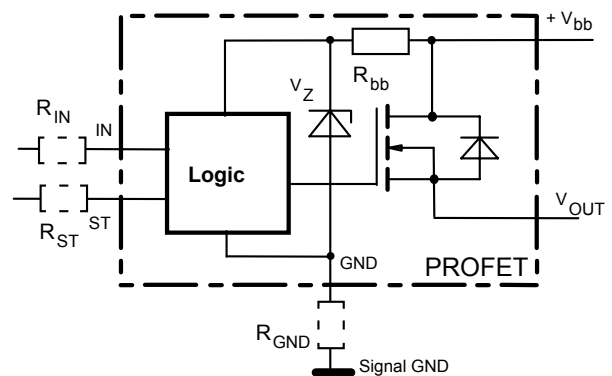


Inductive and overvoltage output clamp



V_{ON} clamped to 58 V typ.

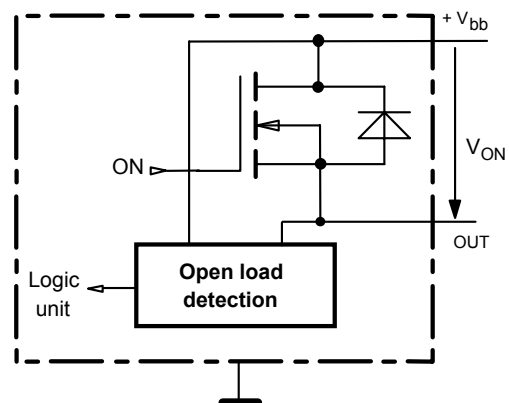
Overvolt. and reverse batt. protection



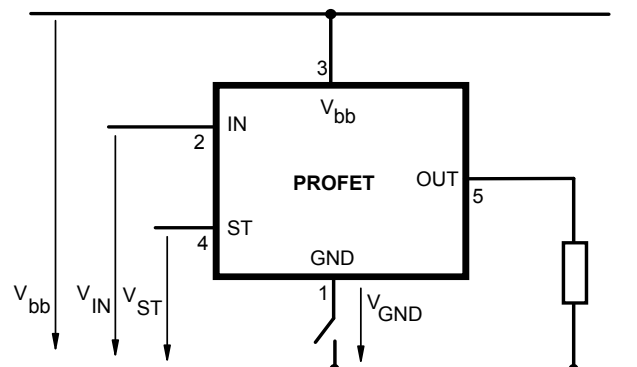
$R_{bb} = 120 \, \Omega$ typ., $V_Z + R_{bb} \cdot 40 \, \text{mA} = 67 \, \text{V}$ typ., add R_{GND} , R_{IN} , R_{ST} for extended protection

Open-load detection

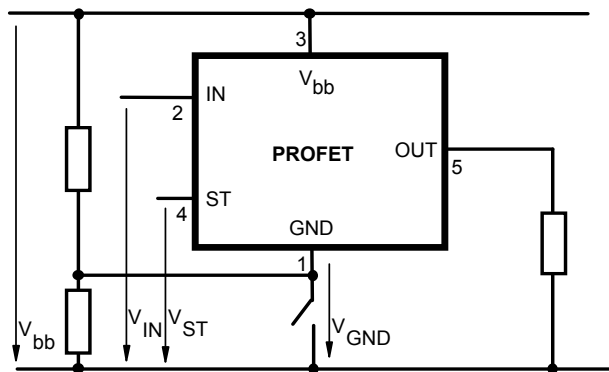
ON-state diagnostic condition: $V_{ON} < R_{ON} \cdot I_{L(OL)}$; IN high



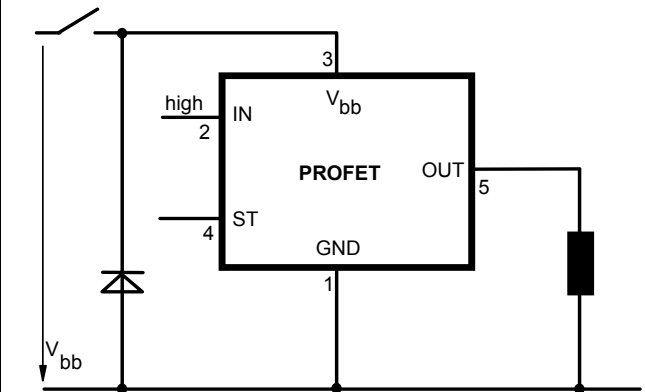
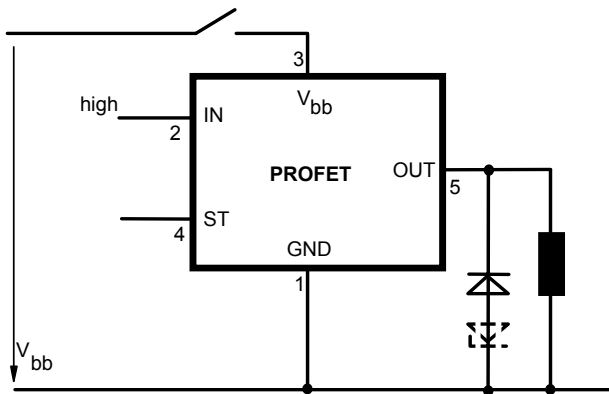
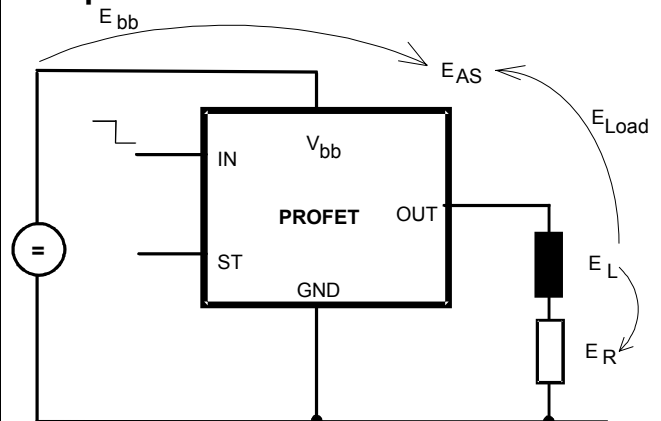
GND disconnect



Any kind of load. In case of Input=high is $V_{OUT} \approx V_{IN} - V_{IN(T+)}$.
 Due to $V_{GND} > 0$, no $V_{ST} = \text{low}$ signal available.

GND disconnect with GND pull up


Any kind of load. If $V_{GND} > V_{IN} - V_{IN(T+)}$ device stays off
Due to $V_{GND} > 0$, no V_{ST} = low signal available.

Vbb disconnect with charged inductive load

Inductive Load switch-off energy dissipation


Energy dissipated in PROFET $E_{AS} = E_{bb} + E_L - E_R$.

$$E_{Load} < E_L, E_L = \frac{1}{2} * L * I_L^2$$

Options Overview

all versions: High-side switch, Input protection, ESD protection, load dump and reverse battery protection , protection against loss of ground

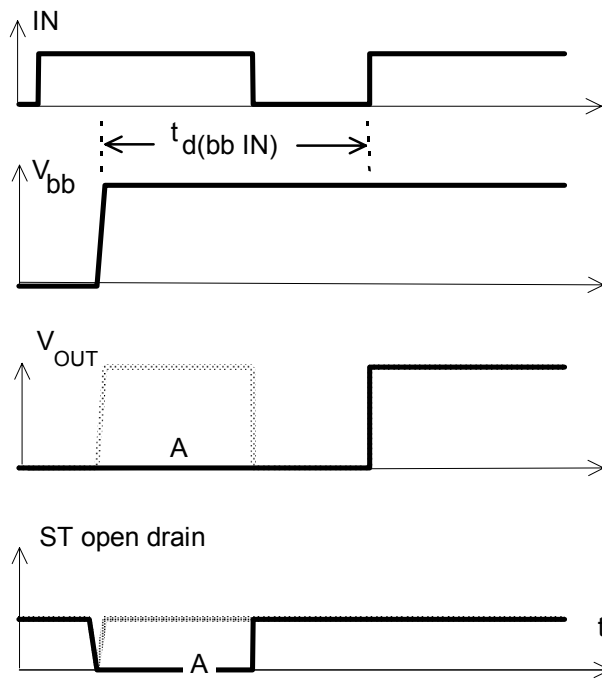
Type	BTS	432E2
Logic version		E
Overtemperature protection $T_j > 150\text{ }^{\circ}\text{C}$, latch function ¹⁵⁾¹⁶⁾ $T_j > 150\text{ }^{\circ}\text{C}$, with auto-restart on cooling		X
Short-circuit to GND protection switches off when $V_{ON} > 8.3\text{ V typ.}^{15)}$ (when first turned on after approx. 200 μs)		X
Open load detection in OFF-state with sensing current 30 $\mu\text{A typ.}$ in ON-state with sensing voltage drop across power transistor		X
Undervoltage shutdown with auto restart		X
Overvoltage shutdown with auto restart		X
Status feedback for		
overtemperature		X
short circuit to GND		X
short to V_{bb}		-17)
open load		X
undervoltage		-
overvoltage		-
Status output type		
CMOS		
Open drain		X
Output negative voltage transient limit (fast inductive load switch off) to $V_{bb} - V_{ON(CL)}$		X
Load current limit		
high level (can handle loads with high inrush currents)		X
medium level		
low level (better protection of application)		

¹⁵⁾ Latch except when $V_{bb} - V_{OUT} < V_{ON(SC)}$ after shutdown. In most cases $V_{OUT} = 0\text{ V}$ after shutdown ($V_{OUT} \neq 0\text{ V}$ only if forced externally). So the device remains latched unless $V_{bb} < V_{ON(SC)}$ (see page 4). No latch between turn on and $t_{d(SC)}$.

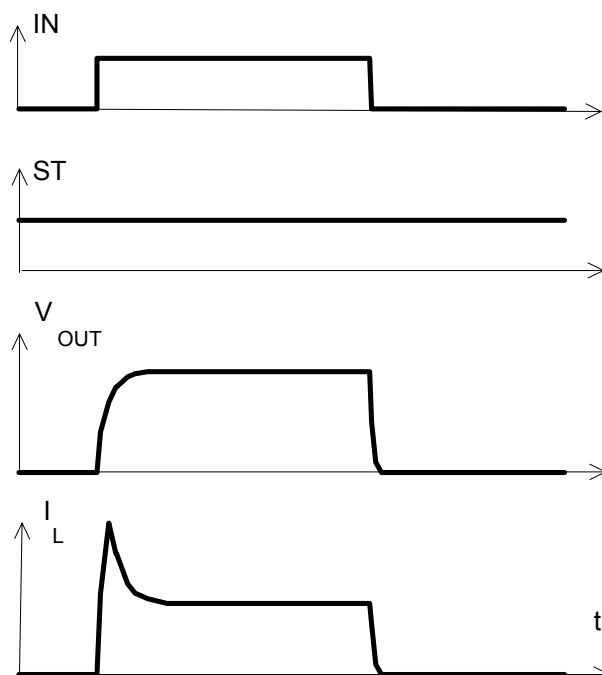
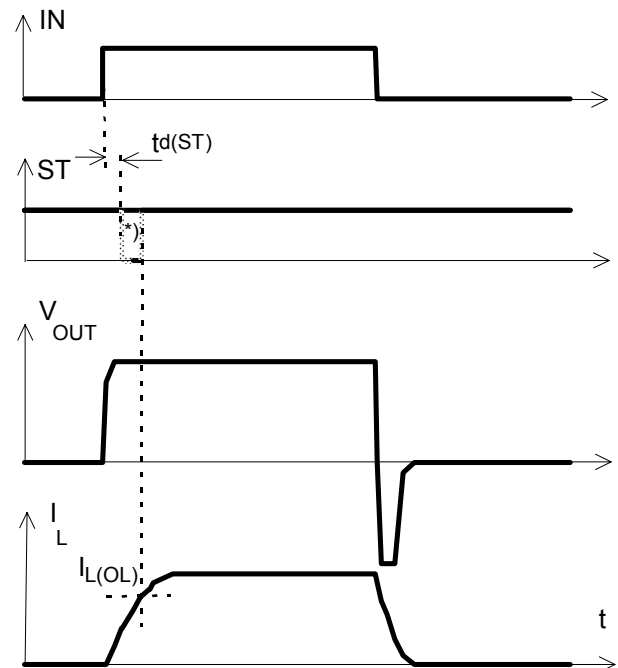
¹⁶⁾ With latch function. Reseted by a) Input low, b) Undervoltage, c) Overvoltage

¹⁷⁾ Low resistance short V_{bb} to output may be detected by no-load-detection

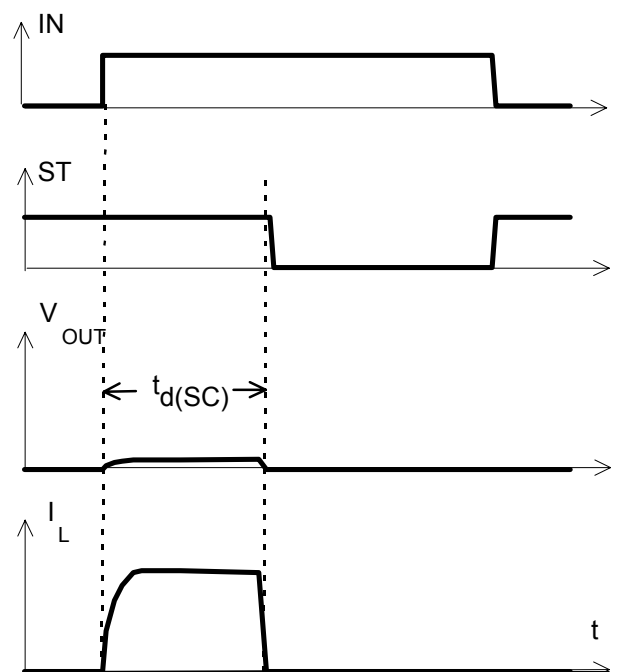
Timing diagrams

Figure 1a: V_{bb} turn on:


in case of too early V_{IN} =high the device may not turn on (curve A)
 $t_{d(bb\ IN)}$ approx. 150 μs

Figure 2a: Switching a lamp,

Figure 2b: Switching an inductive load


*) if the time constant of load is too large, open-load-status may occur

Figure 3a: Turn on into short circuit,


$t_{d(SC)}$ approx. 200 μs if $V_{bb} - V_{OUT} > 8.3\ V$ typ.

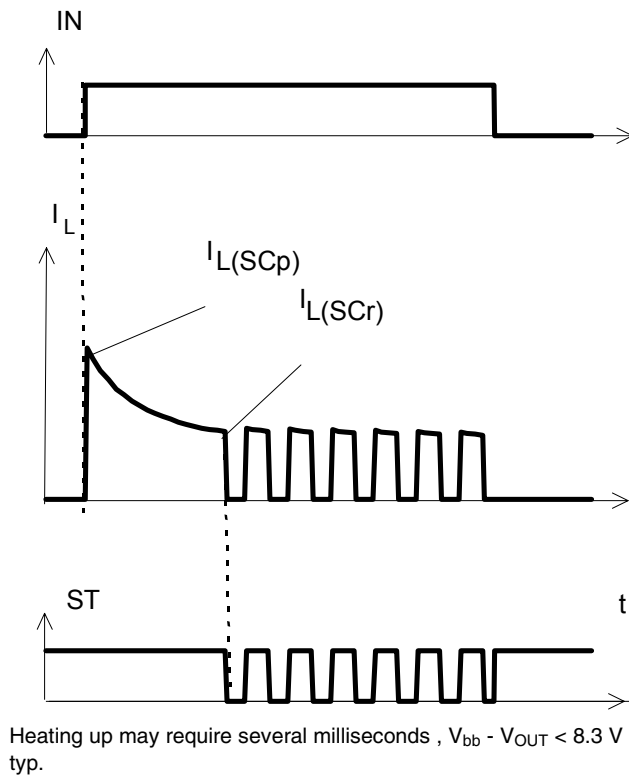
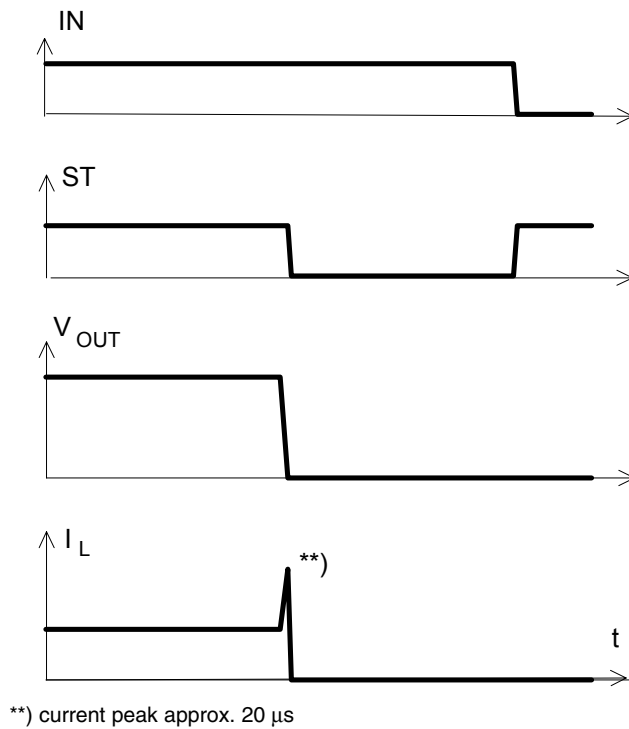
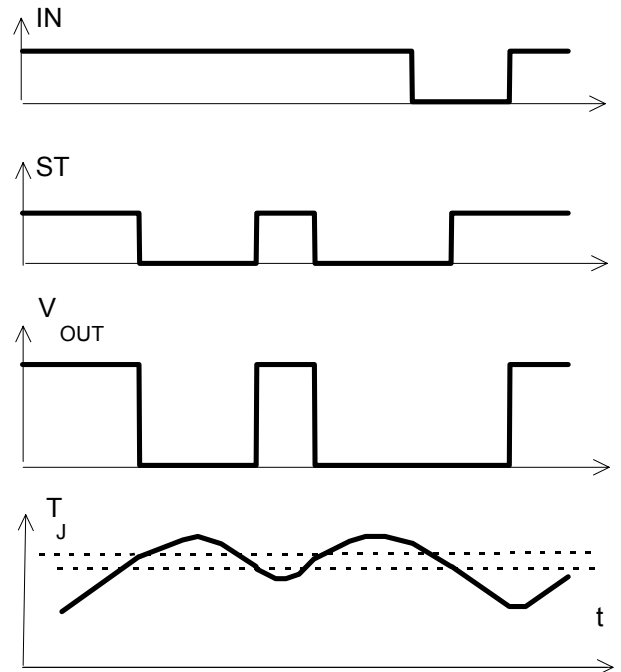
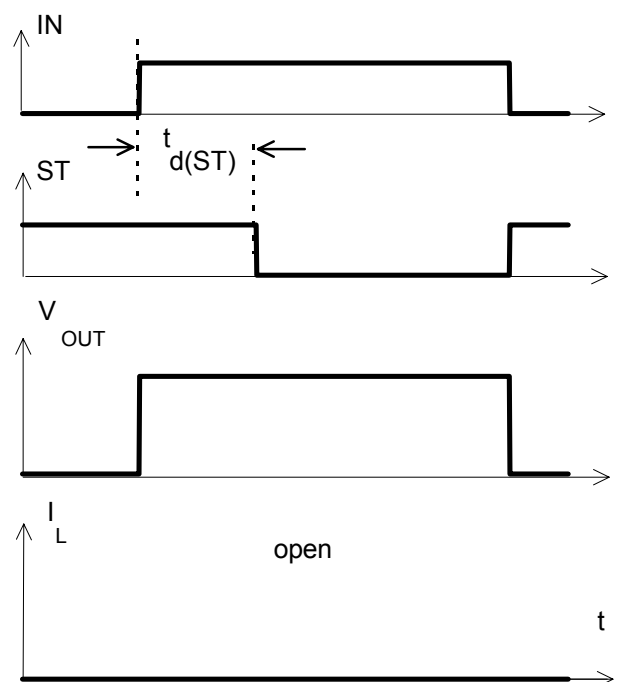
Figure 3b: Turn on into overload,

Figure 3c: Short circuit while on:

Figure 4a: Overtemperature:
Reset if $T_j < T_{jt}$

Figure 5a: Open load: detection in ON-state, turn on/off to open load


Figure 5b: Open load: detection in ON-state, open load occurs in on-state

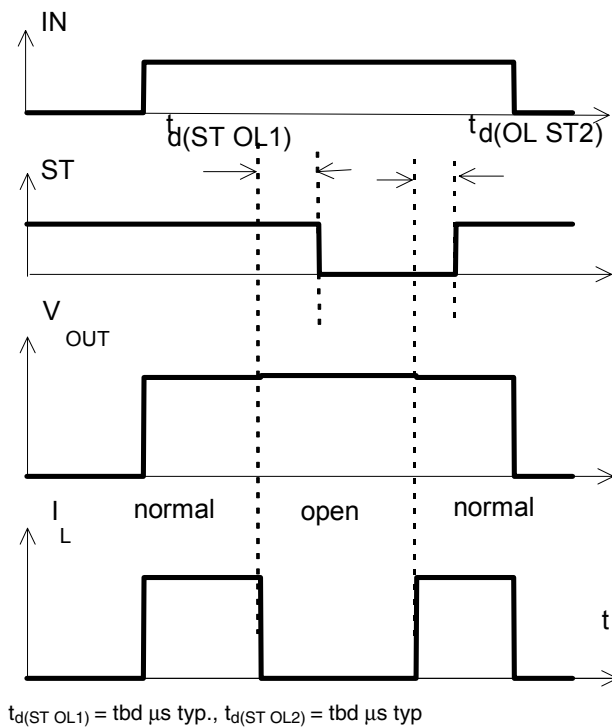


Figure 6a: Undervoltage:

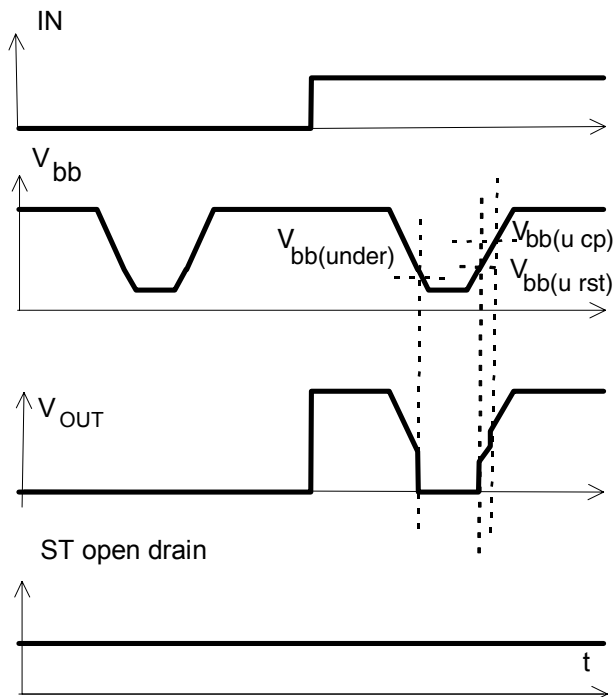


Figure 6b: Undervoltage restart of charge pump

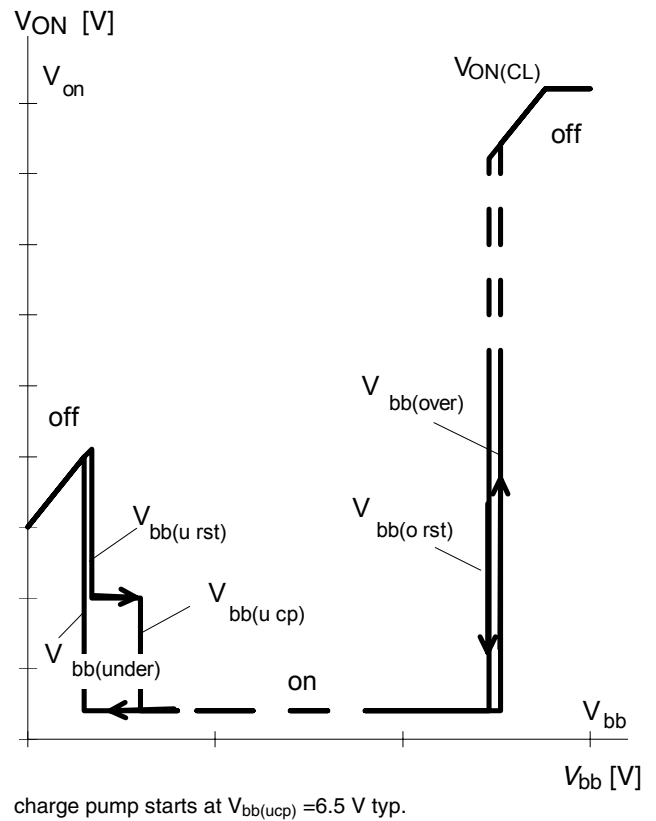
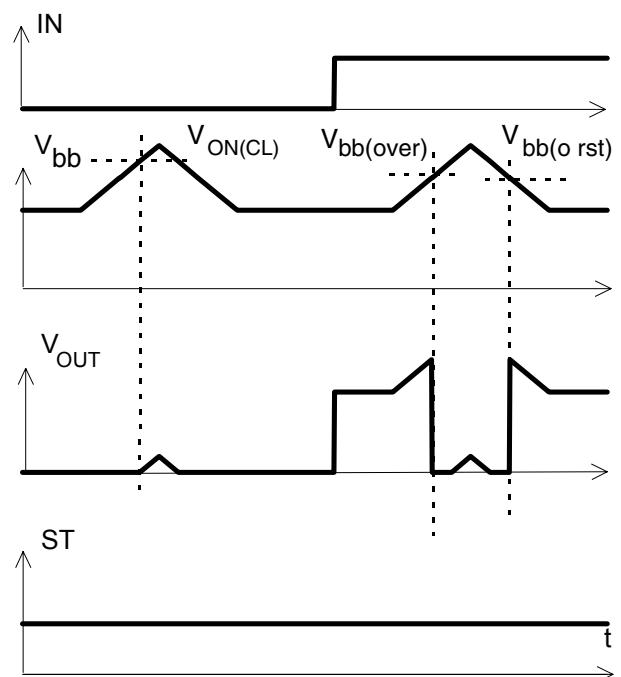


Figure 7a: Overvoltage:

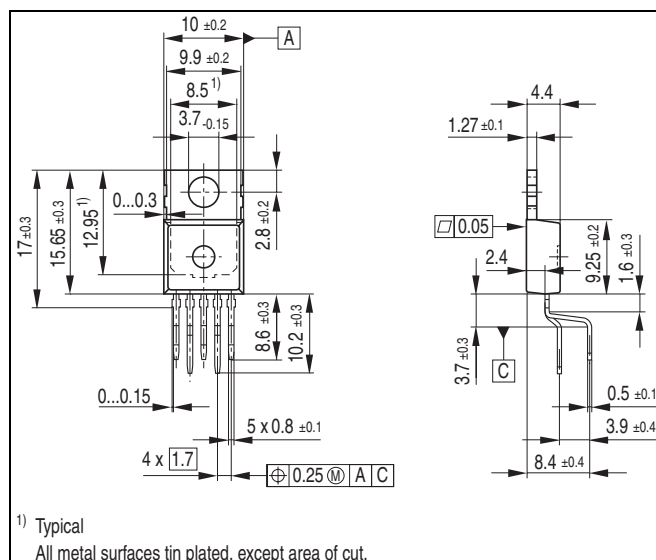


Package and Ordering Code

All dimensions in mm

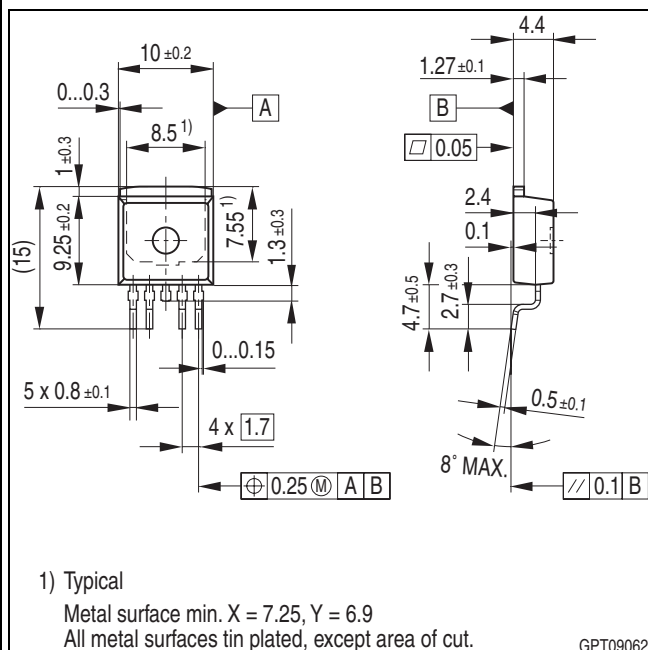
PG-TO220-5-11

BTS 432 E2	
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SMD PG-TO263-5-2

BTS432E2 E3062A	
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Green Product

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

Revision History

Version	Date	Changes
Rev. 1.1	2010-01-26	Page 13: Package drawing for PG-TO220-5-11 corrected.
Rev. 1.0	2009-11-12	RoHS-compliant version of BTS432E2 Removal of straight lead package variant E3043 Page 1, page 13: RoHS compliance statement and Green product feature added Page 1, page 13: Change to RoHS compliant packages; PG-TO220-5-11 for standard (staggered) variant; PG-TO263-5-2 for E3062A variant. Page 2: Thermal resistance junction to ambient for SMD version set to typically 33K/W. Page 2: Pin marking removed. Page 6, 9: Discontinued variants removed from truth table & options overview. Legal disclaimer updated

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